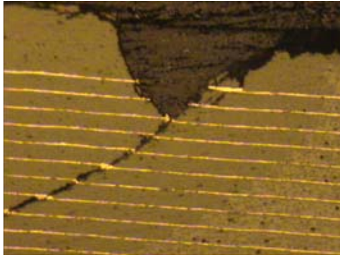
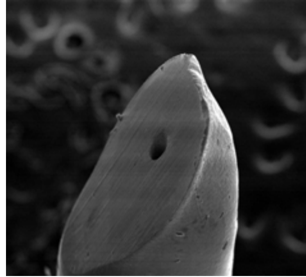
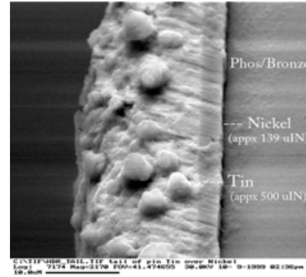
JGAR Lab Services



Metallurgical micrograph showing greater detail micro-sectioning slice of capacitor body.

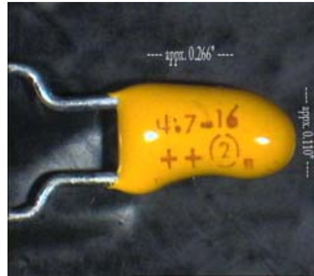


Scanning Electron Microscope Photo of solder missing rosin

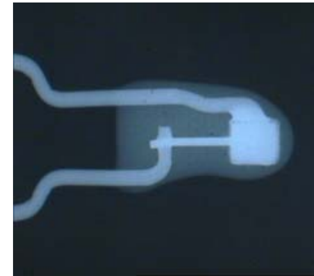


Scanning Electron Microscope Photo of plating thickness

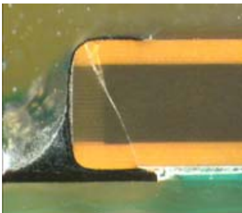
Stereo Microscope with Digital Photography, 1250 times magnification capability



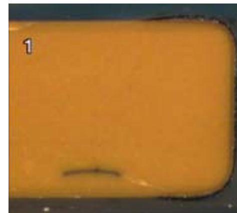
Stereo Microscope Photo of capacitor



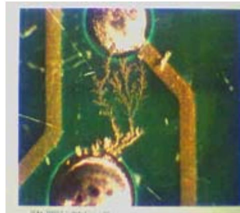
X-Ray of Capacitor



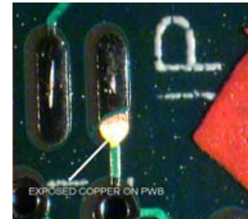
Cracked SMT Capacitor Flex Stress Fracture



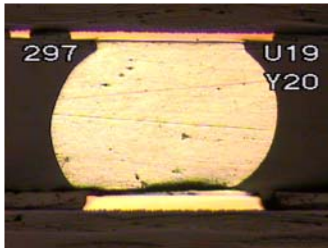
Cracked SMT Capacitor Electrical Overstress



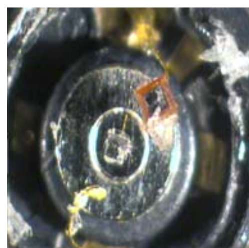
Tin dendrites between nodes



Bare Copper on PWB

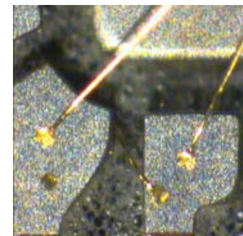


BGA Ball fracture

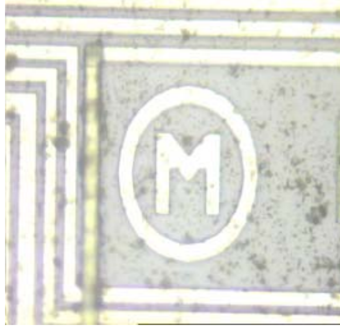


sub-mount detached form mcpcb

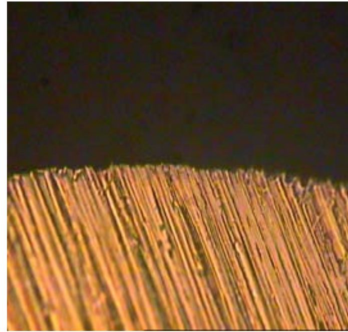
Shear test for BGA



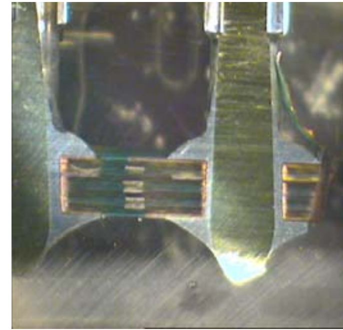
IC – extra bond wire detail



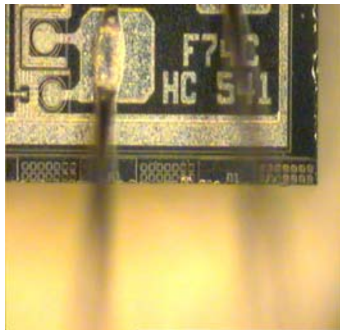
Die under Metallurgical scope



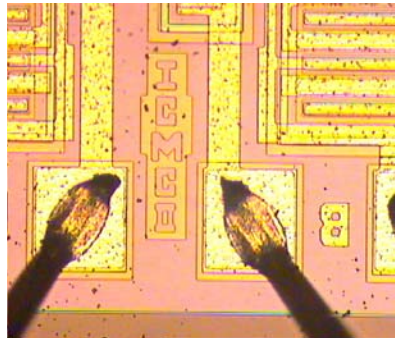
Lead grain structure dull in appearance



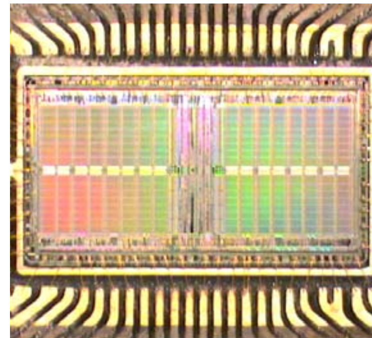
solder pin micro-sectioned



Die viewed after decap

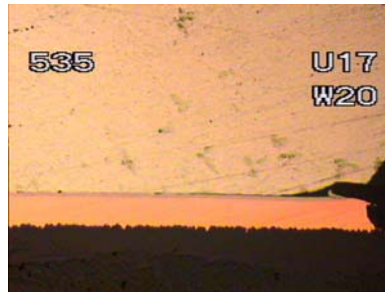


Die markings at 280X

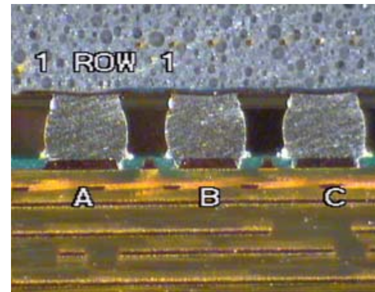


Die viewed under duel microscope

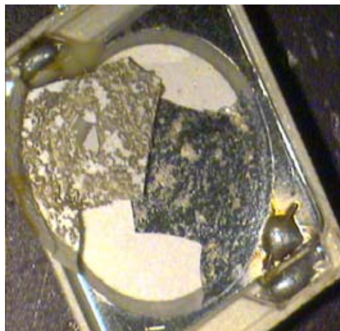
Dye Penetrate shear test



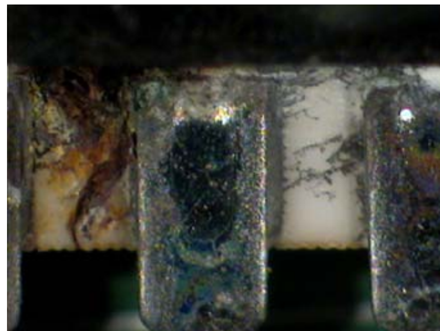
BGA 500X fracture



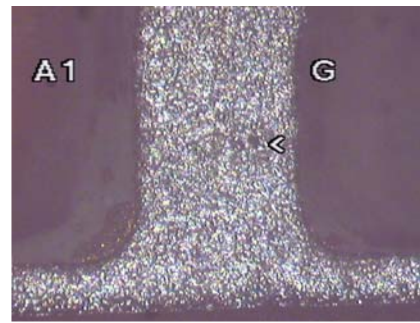
BGA cross-section view



Glue adhesion problem



Dendrites growth



Metallurgical microscope photo detail of die and area of small burned area between G pad and A1 connection